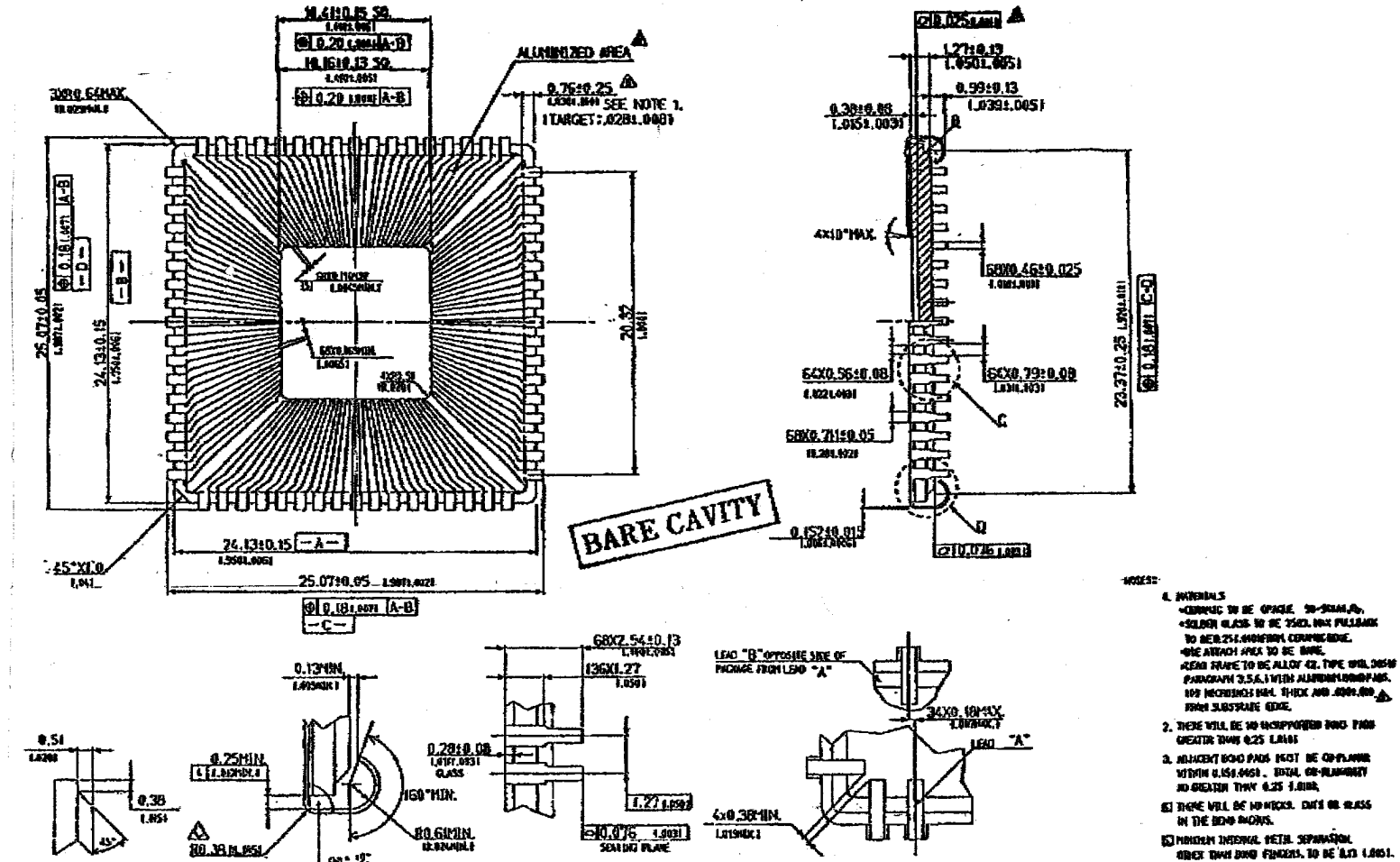


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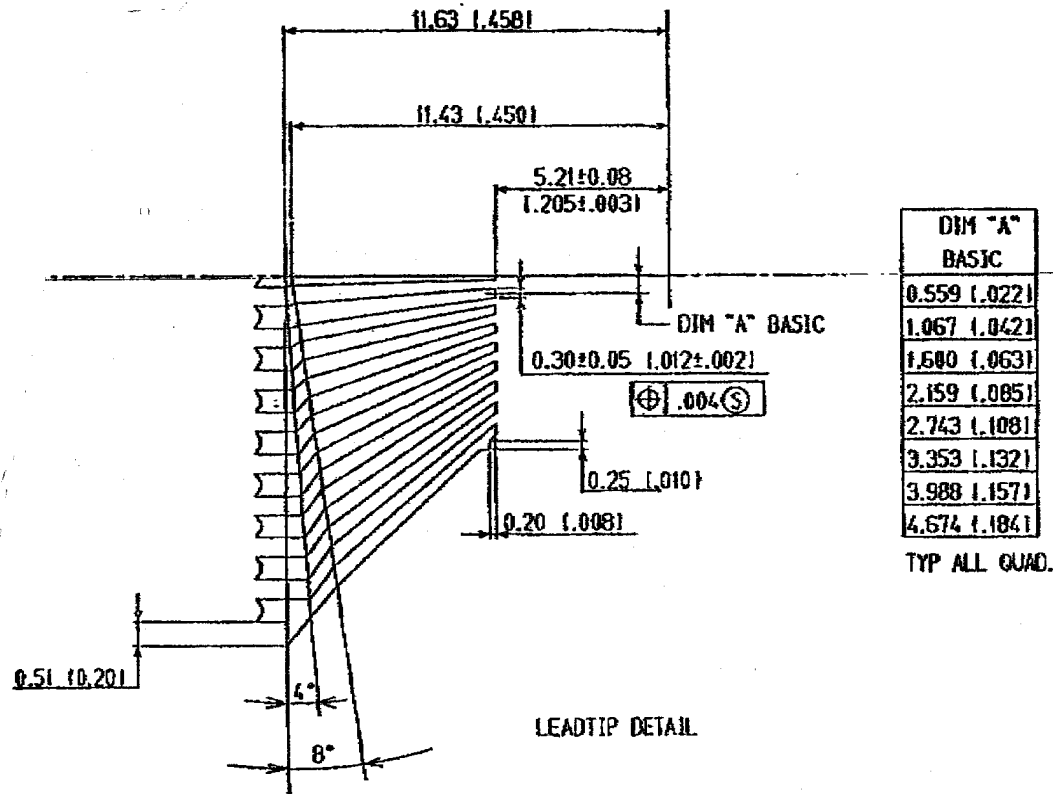


- INCHES
1. DIMENSIONS  
- CENTER TO BE SPACED TO CENTER.  
- SOLDER GLASS TO BE 150.0 MIL PRESSURE TO BE 25.0 MINIMUM CURVED.  
- THE ATTACH AREA TO BE BARE.  
- LEAD FRAME TO BE ALLOY 42, TYPE 100/100 PAR. 100 INCHES MIL THICK AND .0001± FROM SUBSTRATE EDGE.
  2. THERE WILL BE NO UNCOUPLED BOND PADS GREATER THAN 0.25 LEAD.
  3. ADJACENT BOND PADS MUST BE CO-PLANAR WITHIN 0.15±0.005, BOND OR PLACEMENT NO GREATER THAN 0.25 ±.005.
  4. THERE WILL BE NO HICKS, DIPS OR GLASS IN THE BOND PADS.
  5. MINIMUM INTERNAL PITCH SEPARATION DISTANCE TWO BOND PADS TO BE 0.11 ±.005.

SCALE	MATERIAL	FOR USE	X	FILE
1:1	—	UNLESS NOTED	3 X X	68 LCQD BASE
DIMENSION	PROJECTION	CUSTOM		OUR PART NO.
APPROVED	3FG			
APPROVED	3FG	CHECKED	PRECISION	DATE OF
APPROVED	3FG	CHECKED	PRECISION	EXF-3107-Δ 1/2
APPROVED	3FG	CHECKED	PRECISION	CUSTOMER DTD NO.
APPROVED	3FG	CHECKED	PRECISION	



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SCALE	MATERIAL	TOLERANCE	XX	TITLE
8" = 1"			XX	681 CDD LEAD TIP DETAIL
DESCRIPTION	ANGLE	CUSTOM		OUR PART NO.
APPROVED (INCH)	3FG			
APPROVED (MGR)	CHECKED	DRAWN		ENG NO. EXP-3107-Δ
				CUSTOMER ENG NO.



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